



# SY22664

## Single Stage LED driver

### Dimmable, High PF and Low BOM Cost

## General Description

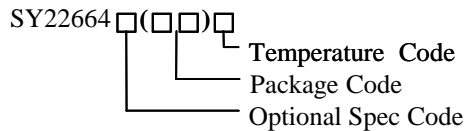
SY22664 is a single-stage driver for LED lighting applications.

SY22664 adopts proprietary techniques to identify whether dimmer applied and dimmer types. Good compatibility is achieved with Leading/Trailing edge dimmer and high PF is achieved without any dimmer.

SY22664 drives the converter in Quasi-Resonant mode to achieve high efficiency. Reliable Open/Short LED protections are integrated.

SY22664 is available in SO8 package.

## Ordering Information



Ordering Number	Package type	Note
SY22664FAC	SO8	--

## Features

- Compatible with Leading Edge/Trailing Edge Dimmer
- High PF without any Dimmer, PF>0.9
- Internal Dimming Curve 5%~100%
- Quasi-Resonant Operation
- Reliable Open/Short LED Protection
- Thermal Fold Back
- Low BOM Cost
- RoHS Compliant and Halogen Free
- Compact Package: SO8

## Applications

- LED Lighting
- Leading Edge Dimming
- Trailing Edge Dimming

## Typical Applications

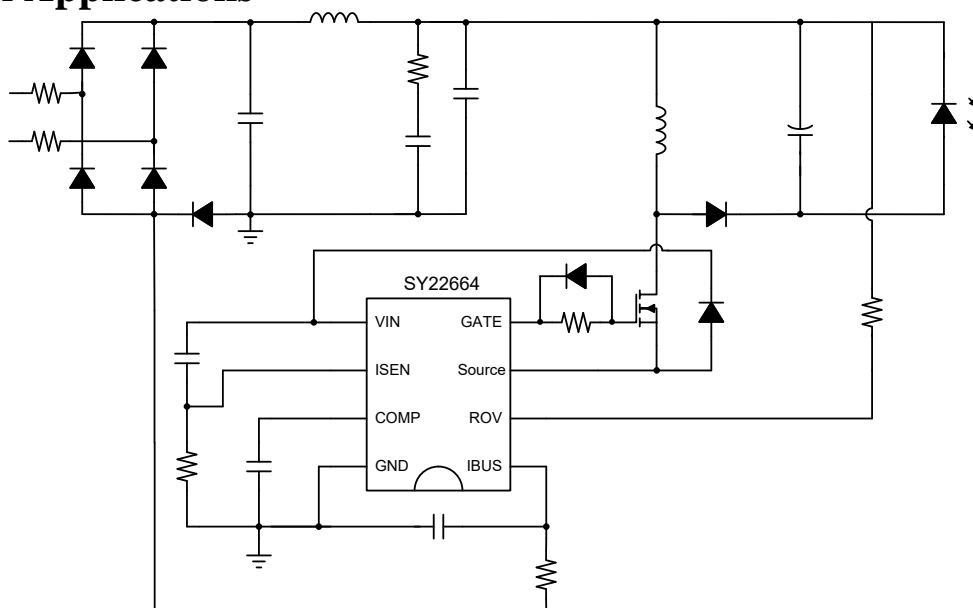
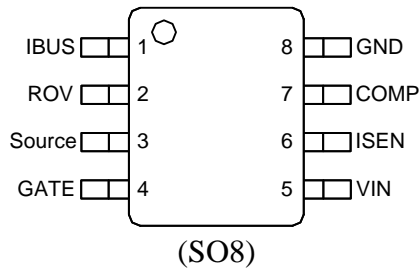


Figure.1 Schematic Diagram

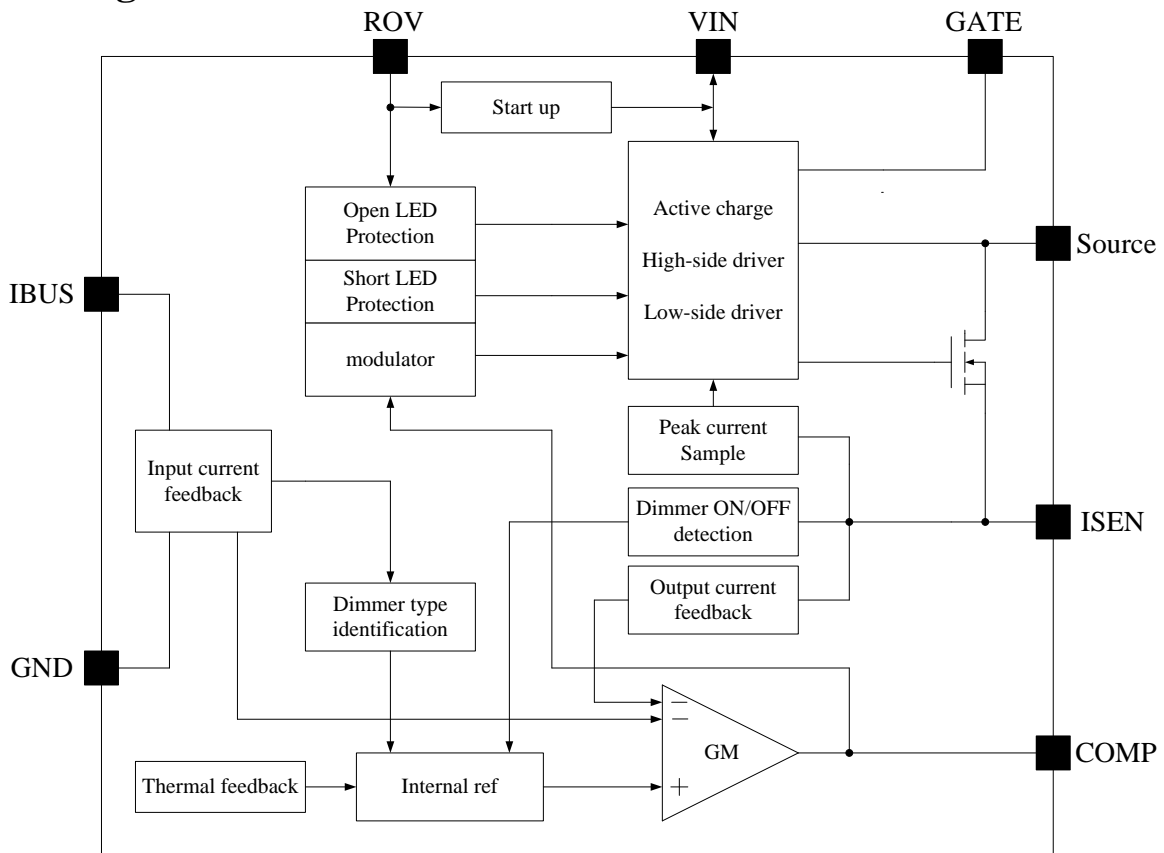
**Pinout** (top view)



Top Mark: **BHKxyz**, (Device code: BHK; *x=year code, y=week code, z=lot number code*)

Pin Name	Pin Number	Pin Description
IBUS	1	Input current sense pin.
ROV	2	Over voltage protection set pin.
Source	3	Connect HV MOSFET Source
GATE	4	Connect HV MOSFET Gate
VIN	5	Bias supply pin.
ISEN	6	Current sense pin.
COMP	7	Output current compensation pin, connect a capacitor to GND.
GND	8	Ground pin.

**Block Diagram**



**Figure.2 Block Diagram**



## Absolute Maximum Ratings (Note 1)

ISEN, COMP	-0.3V~3.6V
IBUS	-1V~0.6V
VIN	-0.3V~20V
ROV	-0.3V~V <sub>VIN</sub> +3V
Source	-0.3V~V <sub>VIN</sub> +1V
GATE	-0.3V~36V
Power Dissipation, @ T <sub>A</sub> = 25°C SO8	1.1W
Package Thermal Resistance (Note 2)	
SO8, $\theta_{JA}$	88°C/W
SO8, $\theta_{JC}$	45°C/W
Junction Temperature Range	-40°C to 165°C
Lead Temperature (Soldering, 10 sec.)	260°C
Storage Temperature Range	-65°C to 150°C

## Recommended Operating Conditions (Note 3)

Ambient Temperature Range	-40°C to 105°C
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## Electrical Characteristics

( $V_{IN}=12V$ ,  $T_A=25^{\circ}C$ , unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Power Supply Section</b>						
VIN Turn-on Threshold	$V_{VIN\_ON}$		13	14	15	V
VIN Turn-off Threshold	$V_{VIN\_OFF}$		7	7.7	8.5	V
Start up Current	$I_{ST}$		3	9	16	$\mu A$
Operation Current	$I_Q$	$V_{ISEN}=0$	340	450	570	$\mu A$
VIN Shunt Current when Protection	$I_{VIN\_Shunt}$		4	5.7	7	mA
<b>ISEN Pin Section</b>						
Internal Reference Voltage	$V_{REF\_IO}$		294	300	306	mV
Current Limit Voltage	$V_{ISEN\_LIM}$		320	350	380	mV
Threshold for Conduction Duty Detection	$V_{ISEN\_TH}$			50		mV
<b>ROV Pin Section</b>						
OVP Coefficient	$K_{OVP}$		79	85.5	90	$\mu A$
<b>IBUS Pin Section</b>						
Regulated Input Current	$I_{IBUS\_REF}$		26	30	34	mA
<b>PWM Logic Section</b>						
Minimum PWM ON Time	$T_{ON\_MIN}$			430		ns
Minimum PWM OFF Time	$T_{OFF\_MIN}$			2		$\mu s$
Maximum PWM ON Time	$T_{ON\_MAX}$			6.5		$\mu s$
Maximum PWM OFF Time	$T_{OFF\_MAX}$	dimmer ON		140		$\mu s$
<b>Thermal Section</b>						
Thermal Fold Back Threshold	$T_{FB}$			140		$^{\circ}C$
Thermal Shut Down Temperature	$T_{SD}$			155		$^{\circ}C$

**Note 1:** Stresses beyond the “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

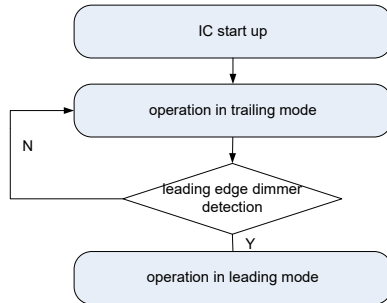
**Note 2:**  $\theta_{JA}$  is measured in the natural convection at  $T_A = 25^{\circ}C$  on a low effective single layer thermal conductivity test board of JEDEC 51-3 thermal measurement standard. Test condition: Device mounted on 2” x 2” FR-4 substrate PCB, 2oz copper, with minimum recommended pad on top layer and thermal vias to bottom layer ground plane

**Note 3:** The device is not guaranteed to function outside its operating conditions.

## Operation

### Operation Flow

The IC provides different operation modes for different dimmer types.



Dimmer type detection:

IC detects input current variation to identify the dimmer type.

Trailing mode:

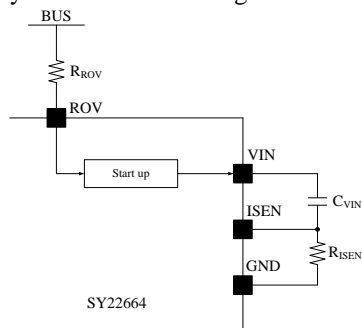
The IC discharges the input capacitor quickly when dimmer OFF is detected, which ensures the compatibility for trailing edge dimmer.

Leading mode:

The IC guarantees the input current higher than the latching current and holding current of leading edge dimmer, which ensures the compatibility for leading edge dimmer.

### Start up

After AC supply is powered on, the capacitor  $C_{VIN}$  across VIN and GND pin is charged up by BUS voltage through the resistor  $R_{ROV}$ . Once  $V_{VIN}$  rises up to  $V_{VIN\_ON}$ , the internal blocks start to work and  $V_{COMP}$  is pre-charged to certain value. After start up,  $V_{VIN}$  is sustained by internal active charge block.



$C_{VIN}$  is selected to obtain an ideal start up time  $t_{ST}$ , the recommended formula is as below:

$$C_{VIN} = \frac{\left(\frac{V_{BUS}}{R_{ROV}} - I_{ST}\right) \times t_{ST}}{V_{VIN\_ON}}$$

### Shut Down

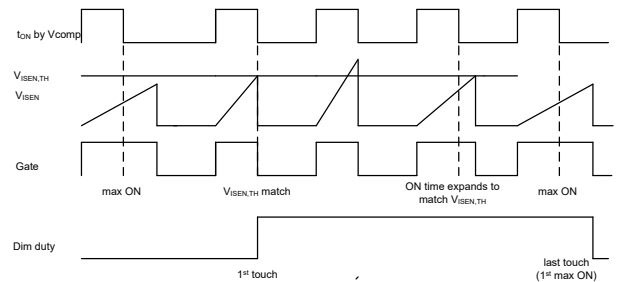
After AC supply is powered off, the energy stored in the BUS capacitor will be discharged. When the internal active charge block cannot supply enough energy to VIN pin,  $V_{VIN}$  will drop down. Once  $V_{VIN}$  is below  $V_{VIN\_OFF}$ , the IC will stop working and  $V_{COMP}$  will be discharged to zero.

### LED Current Setting

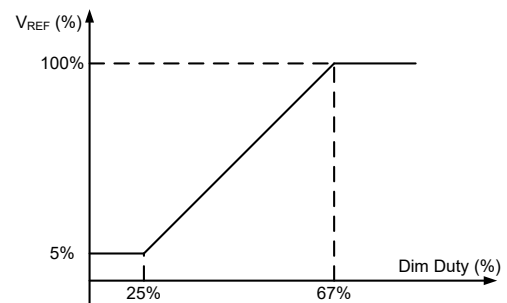
The LED current is set by the resistor  $R_{ISEN}$  across ISEN and GND. The relationship is as below:

$$I_{LED} = \frac{V_{REF}}{2 \times K_{IO} \times R_{ISEN}}$$

### Conduction Angle Detection



The threshold  $V_{ISEN\_TH}$  on ISEN pin is applied to detect the conduction duty.  $t_{ON}$  is controlled by  $V_{COMP}$  generally to achieve high PF, which is relatively stable. If  $V_{ISEN}$  cannot reach  $V_{ISEN\_TH}$  by  $V_{COMP}$ ,  $t_{ON}$  will expand to reach  $V_{ISEN\_TH}$  till max  $t_{ON}$ . When  $V_{ISEN}$  is higher than  $V_{ISEN\_TH}$ , dimmer ON is identified; when  $V_{ISEN}$  is lower than  $V_{ISEN\_TH}$ , although max  $t_{ON}$  is output, dimmer OFF is identified. The dim duty is transferred to output current by the curve below.



## Open LED

The protection voltage  $V_{OVP}$  for open LED is set by the resistor  $R_{ROV}$  across BUS and ROV pin.

$$V_{OVP} = K_{OVP} \times R_{ROV}$$

If Over Voltage is triggered, the PWM output is stopped and  $V_{VIN}$  is discharged by  $I_{VIN\_shunt}$ . The IC operates in hiccup mode.

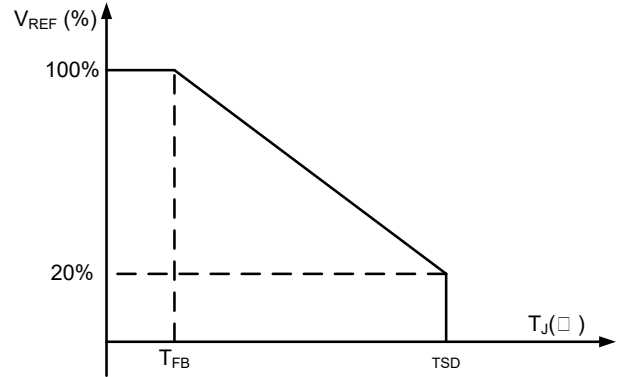
## Short LED

If LED is short, the PWM output is stopped and  $V_{VIN}$  is discharged by  $I_{VIN\_shunt}$ . The IC operates in hiccup mode.

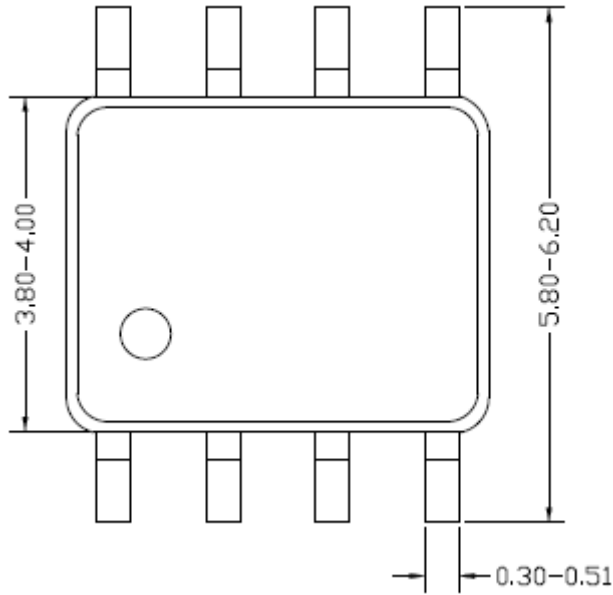
## Thermal Treatment

Thermal fold back is adopted in this IC. Thermal fold back curve is shown as below.

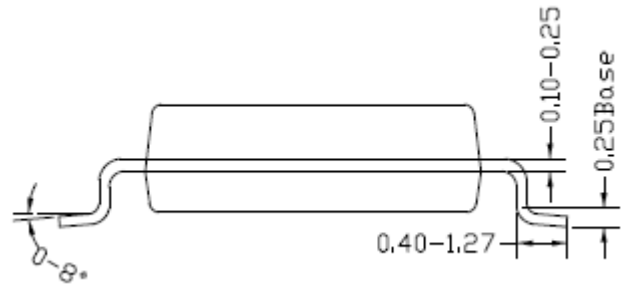
When the junction temperature rises high, internal current reference decreases first; if the junction temperature still rises up over  $T_{SD}$ , IC will be shut down.



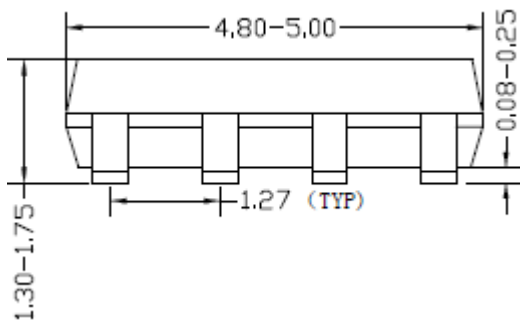
**SO8 Package outline & PCB layout design**



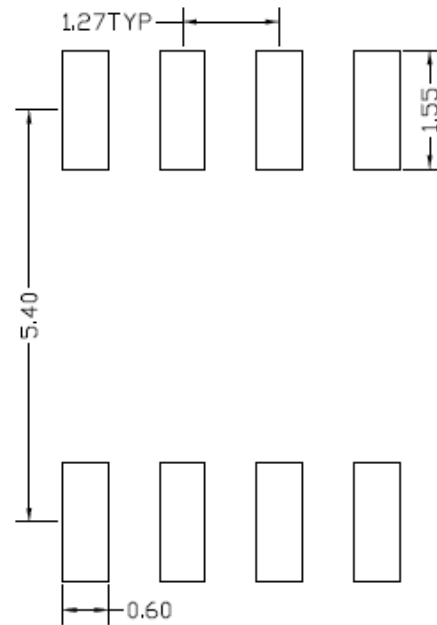
**Top view**



**Side view**



**Front view**

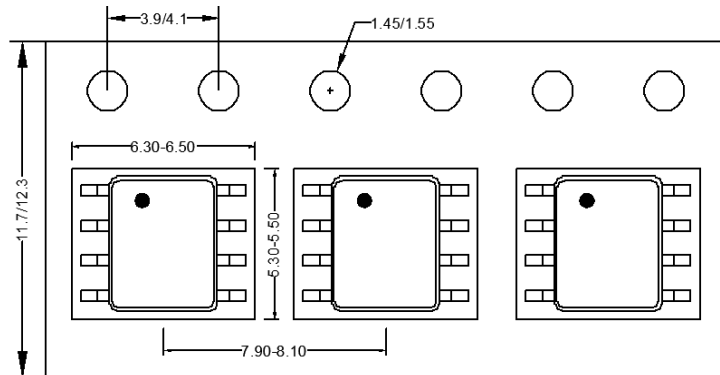


**Recommended Pad Layout  
(Reference only)**

**Notes: All dimension in millimeter and exclude mold flash & metal burr.**

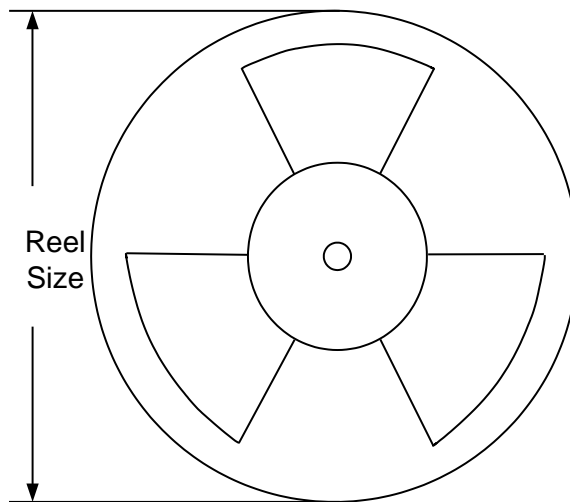
## Taping & Reel Specification

### 1. Taping orientation for packages (SO8)



Feeding direction →

### 2. Carrier Tape & Reel specification for packages



Package type	Tape width (mm)	Pocket pitch(mm)	Reel size (Inch)	Trailer length(mm)	Leader length (mm)	Qty per reel
SO8	12	8	13"	400	400	2500

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## Revision History

The revision history provided is for informational purpose only and is believed to be accurate, however, not warranted. Please make sure that you have the latest revision.

<b>Date</b>	<b>Revision</b>	<b>Change</b>
July 23, 2019	Revision 0.9	Initial Release

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